

In the specification:

On page 1, please replace paragraph 3 with the following:

Since a relatively large distance (compared to the size of the chip) has to be covered between the site of removal from the film carrying the ~~water~~ wafer and a predetermined location on the substrate, which comprises the bond contacts for bonding the chip to the substrate, a technically complicated flip-chip bonder machine is required in order to ensure precise positioning of the chip or dice on the substrate to be equipped therewith. Such machines have high manufacturing costs, increased maintenance requirements on account of their complicated design and a low throughput on account of the long transport paths for the flip-chips.

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